

Features

- ◆ Lead free type.
- ◆ Compact size for 0402
- ◆ Insulator over coat keeps excellent low and stable leakage current.
- ◆ Quick response time(<1ns).
- ◆ Low Clamping Voltage.
- ◆ Meet IEC 61000-4-2 standard.
 - Contact discharge mode:typical $\pm 15\text{kv}$
 - Air discharge mode:typical $\pm 20\text{kv}$



Applications

- ◆ Application for Mother Board, Notebook, cellular Phone, PDA, handheld device, DSC, DV, Scanner, and Set-Top Box etc.

Part Numbering

CV	3	xx	030	T
A	B	C	D	E

A:ASIM Serise Name

B:Dimension,3:0402

C: V_{DC}

D:030:3.0PF(+100%~-50%)

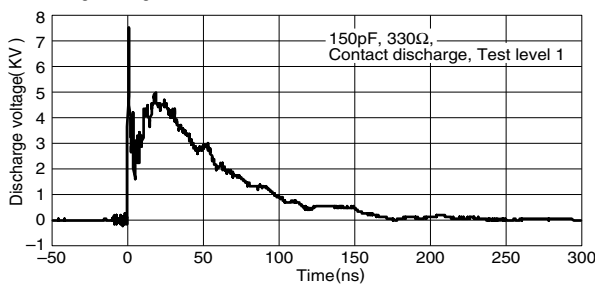
E: Tape

Specifications

Part Number	Rated Voltage V_{DC} (V)	$V_{BR}@1mA$ (V) min	V_{Clamp} ESD (V) typ	C_i (pF) @1MHz, 0V typ	Leakage Current I_L (μA)
CV3JP030T	3.3	22.0	70.0	3.0	3.0
CV3JE030T	5.0	22.0	70.0	3.0	3.0
CV3JF030T	6.0	22.0	70.0	3.0	3.0
CV3JI030T	9.0	22.0	70.0	3.0	3.0
CV3AB030T	12.0	22.0	70.0	3.0	10.0
CV3AD030T	14.0	22.0	70.0	3.0	10.0
CV3AF030T	16.0	22.0	70.0	3.0	10.0

Electrostatic absorption charateristic

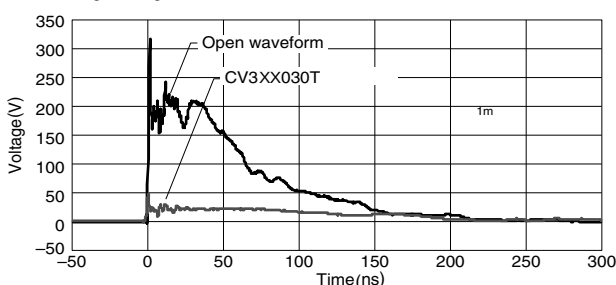
Discharge voltage waveform



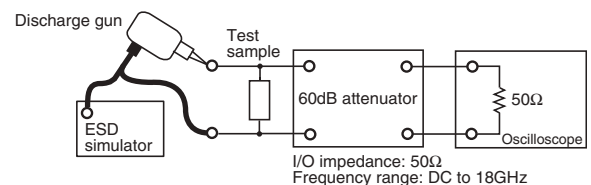
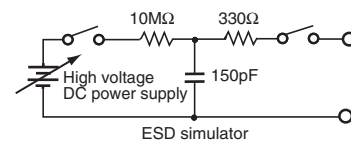
Current wave parameter [IEC61000-4-2]

level	ESD Charging voltage (kV)	Discharge 1 peak current (A)	Rise time (ns)
1	2	7.5	0.7 to 1.0
2	4	15	0.7 to 1.0
3	6	22.5	0.7 to 1.0
4	8	30	0.7 to 1.0

Discharge voltage waveform

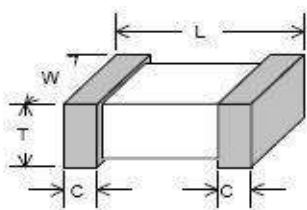


CAPACITANCE vs. FREQUENCY CHARACTERISTICS



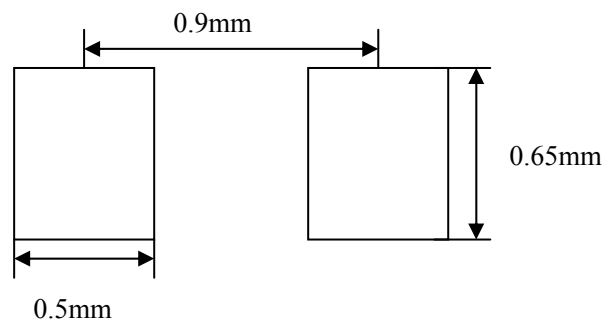
IMPEDANCE vs. FREQUENCY CHARACTERISTICS

Dimensions



Unit:mm

Size EIA(EIAJ)	(0402)
L	1.00±0.15
W	0.50±0.10
T	0.50±0.10
C	0.25±0.15



Solder thickness 0.15 to 0.2mm

General Technical Data

Operating Temperature	-55 ~ +125°C
Storage Temperature	-55~ +125°C
Response Time	<1 ns
Solderability	245±5°C,3±1sec.

Environmental Performance

Item	Specifications	Test Condition
Bias Humidity	$\Delta V_v / V_v \leq \pm 10\%$	90%RH,40°C,Working Voltage,1000hrs
Thermal Shock		-55°C to 125°C,30min.cycle,5 cycles
Full Load Voltage		Working Voltage ,125°C,1000hrs
Solder Leach Resistance	(1) $\Delta V_v / V_v \leq \pm 10\%$ (2) $I_L \leq 1nA$ at Working Voltage (3)Solder Wetting Area≥95%	260±5°C,10 ±1sec.